

Title (en)

ELECTRONIC COMPONENT AND COATING AGENT

Title (de)

ELEKTRONISCHES BAUELEMENT UND BESCHICHTUNGS-MITTEL

Title (fr)

COMPOSANT ELECTRONIQUE ET AGENT DE REVETEMENT

Publication

EP 1133800 A1 20010919 (DE)

Application

EP 00971253 A 20000921

Priority

- DE 0003290 W 20000921
- DE 19945131 A 19990921

Abstract (en)

[origin: WO0122501A1] The invention relates to an electronic component comprising, in predetermined areas, soldered regions that are arranged on at least one outer surface, whereby the component is coated on its surface that is not formed by the soldered regions with a layer that prevents the adherence of soldering agents thereto. The invention also relates to a coating agent for reducing the amount of solder tailings.

IPC 1-7

H01L 33/00; **H05K 3/34**

IPC 8 full level

B23K 1/00 (2006.01); **H01L 23/00** (2006.01); **H01L 23/12** (2006.01); **H01L 31/02** (2006.01); **H01L 33/48** (2010.01); **H05K 3/34** (2006.01); **B23K 101/36** (2006.01); **H01L 33/38** (2010.01); **H01L 33/40** (2010.01); **H01L 33/62** (2010.01)

CPC (source: EP KR)

H01L 23/28 (2013.01 - KR); **H01L 33/486** (2013.01 - EP); **H01L 33/56** (2013.01 - EP); **H05K 3/3442** (2013.01 - EP); **H01L 33/62** (2013.01 - EP); **H01L 2224/05568** (2013.01 - EP); **H01L 2224/05573** (2013.01 - EP); **H01L 2224/16** (2013.01 - EP); **H01L 2924/00014** (2013.01 - EP); **H05K 2201/10106** (2013.01 - EP); **H05K 2201/10636** (2013.01 - EP); **H05K 2201/2081** (2013.01 - EP); **Y02P 70/50** (2015.11 - EP)

Citation (search report)

See references of WO 0122501A1

Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

WO 0122501 A1 20010329; DE 19945131 A1 20010412; EP 1133800 A1 20010919; JP 2003510818 A 20030318; JP 2005136438 A 20050526; KR 20010107975 A 20011207

DOCDB simple family (application)

DE 0003290 W 20000921; DE 19945131 A 19990921; EP 00971253 A 20000921; JP 2001525774 A 20000921; JP 2005009629 A 20050117; KR 20017006316 A 20010518